



PK952(v1.0) March 20, 2018

100% Material Declaration Data Sheet for Spartan-7 FGGA676

Average Weight : 3.0360 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00		0.044429	1.463%
					0.044429	
Die Attach Material	Silver	7440-22-4	74.00		0.006131	0.273%
	Bismaleimide monomer	trade secret	15.00		0.001243	
	Methacrylate resin	trade secret	7.50		0.000621	
	Additive	trade secret	3.00		0.000249	
	Proprietary	trade secret	0.50		0.000041	
Mold Compound					1.417555	46.692%
	Epoxy Resin A	Trade secret	3.00		0.042527	
	Epoxy Resin B	Trade secret	3.00		0.042527	
	Phenol Resin	Trade secret	3.00		0.042527	
	Silica(Amorphous) A	60676-86-0	72.45		1.027019	
	Silica(Amorphous) B	7631-86-9	15.00		0.212633	
	Metal Hydroxide	Trade secret	3.00		0.042527	
Carbon black	1333-86-4	0.55		0.007797		
Copper Wire					0.008631	0.284%
	Copper	7440-50-8	98.08		0.008465	
	Palladium	7440-05-3	1.80		0.000155	
Solder Ball	Gold	7440-57-5	0.12		0.000010	
					0.564707	18.600%
	Tin	7440-31-5	96.50		0.544942	
Substrate	Silver	7440-22-4	3.00		0.016941	
	Copper	7440-50-8	0.50		0.002824	
					0.992393	32.688%
	Solder mask	trade secret	5.24		0.051962	
	BT Core	trade secret	38.68		0.383868	
	Continuous Filament Fiber Glass	65997-17-3	20.01		0.198588	
	Gold	7440-57-5	1.65		0.016365	
	Nickel	7440-02-0	10.57		0.104856	
	Copper Foil	7440-50-8	15.81		0.156868	
Copper plating	7440-50-8	0.27		0.002660		
PrepregGHPL830NXA	N/A	7.78		0.077228		

Revision History

Date	Version	Description of Revisions
3/20/2018	1.0	Initial Xilinx release.